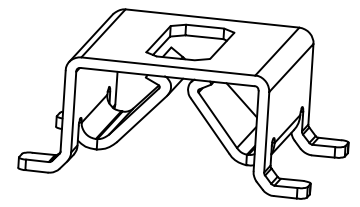
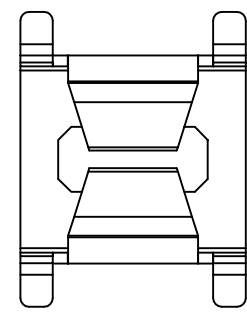
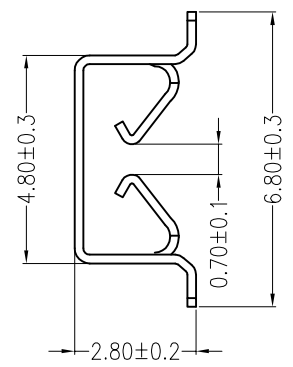
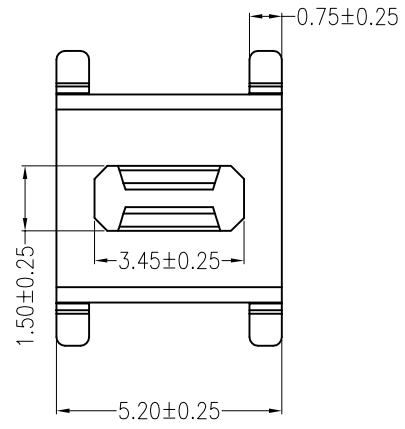
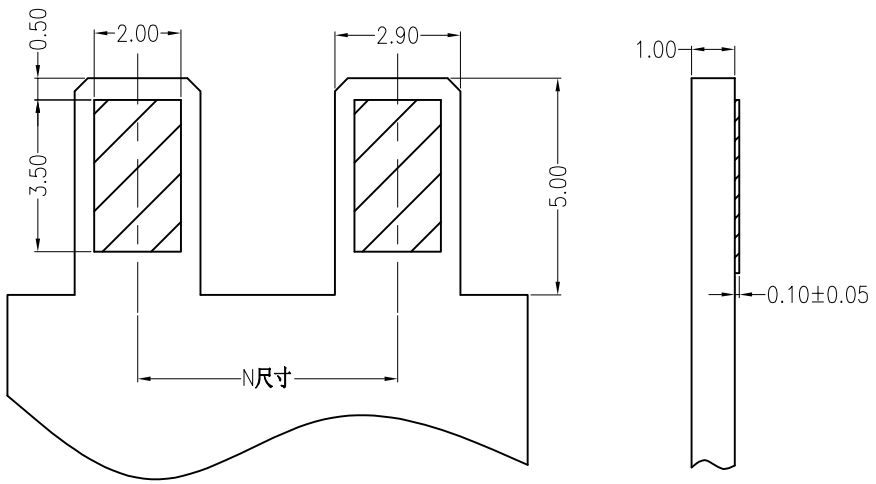


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30

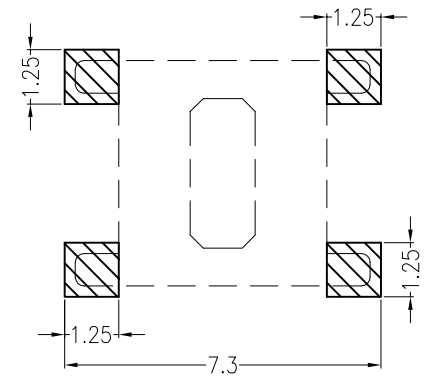


主要技术参数 Main Specifications

板 厚 (thickness): 1.0mm
 接触电阻 (Contact resistance): $\leq 20m\Omega$
 绝缘电阻 (Insulation resistance): $\geq 800M\Omega$
 额定电压 (Rated voltage): 250 V AC DC
 额定电流 (Rated current): 1.0A AC DC
 耐 电压 (Withstand Voltage): 1500V AC/minute
 温度范围 (Temperature Range): $-45^{\circ}C \sim +125^{\circ}C$



Mating PCB detail



Board Layout

ORDER INFORMATION:

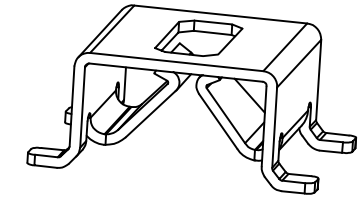
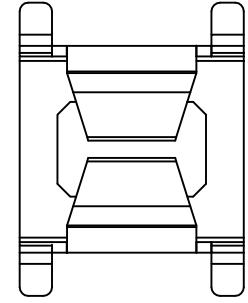
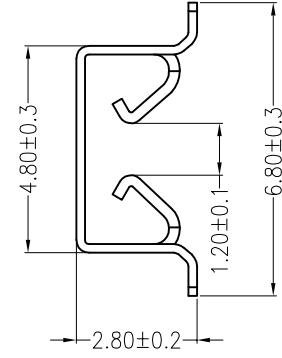
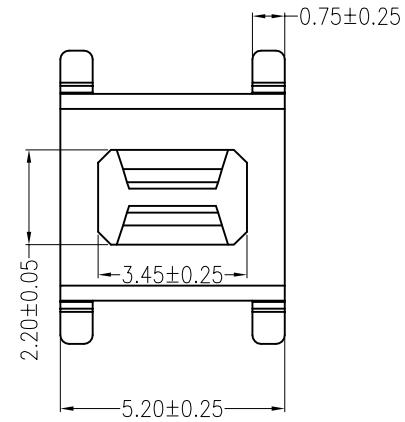
L031-1.0-T2CB-R

PART No.		PACKAGING:
No. FOR PCB:		R=REEL
1.0mm		P=PE
PLASTIC MATERIAL:		PLATING:
T2C=PBR (BEIGE)		B=MATTE Sn

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
A	CONTACT	1 PCS	PhosphorBronze	MATTE Sn-plated

广东科斯达电子科技有限公司 GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.		TITLE: -	
X.±0.5	X.±5'	USE:	PART NO.:
.X±0.3	.X±2'	CUSTOMER	L031-1.0-T2CB-R
.XX±0.25	.XX±1'	APPD:	DWG NO.:
--	--	邵敬和	GCCP-0055
⊕	∠	CHKD:	SCALE
UNITS:	DR:	田峰	1 : 1
mm	蒋建银		SHEET
			1 / 1

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	李润	2016.04.19



主要技术参数 Main Specifications

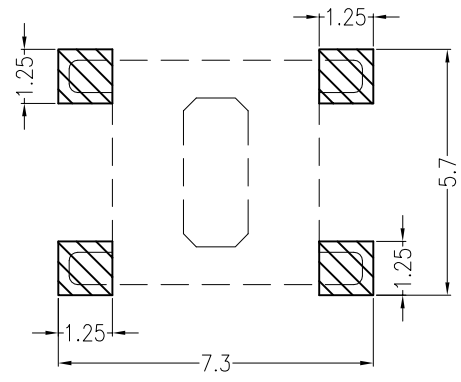
板 厚 (thickness): 1.6mm
 接触电阻 (Contact resistance): $\leq 20m\Omega$
 绝缘电阻 (Insulation resistance):
 额定电压 (Rated voltage): 250 V AC DC
 额定电流 (Rated current): 1.0A AC DC
 耐 电 压 (Withstand Voltage):
 温度范围 (Temperature Range):

ORDER INFORMATION:

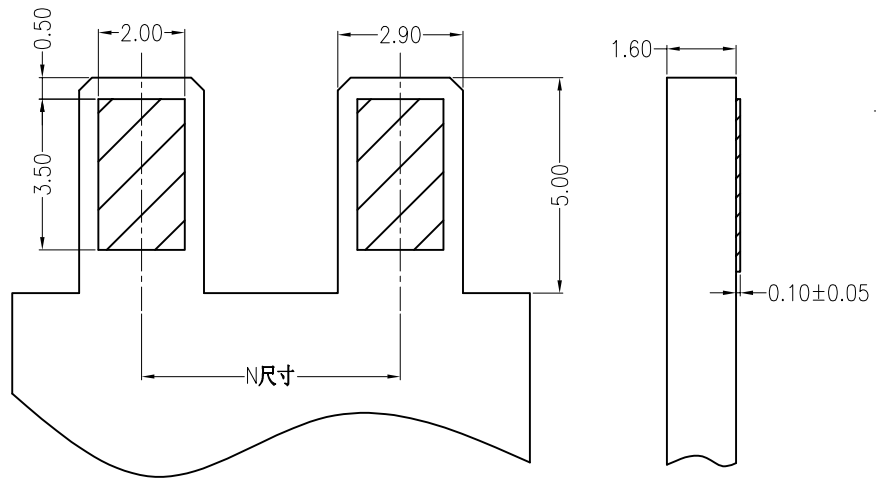
L031-1.6-01-T2CB-R

PART No. _____
 No. FOR PCB: _____
 1.6mm
 No. FOR CIRCUITS: _____
 01


PACKAGING:
 R=REEL
 P=PE
 PLATING:
 B=MATTE Sn
 PLASTIC MATERIAL:
 T2C=PBR (BEIGE)



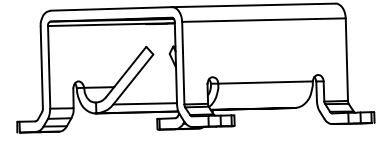
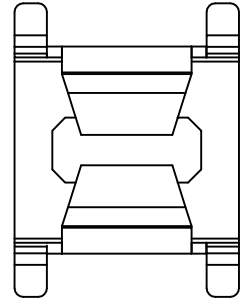
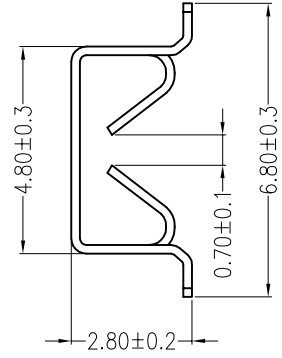
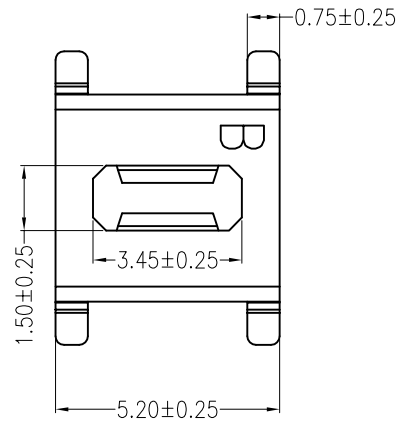
Board Layout



Mating PCB detail

ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
C				
B				
A	CONTACT	1 PCS	PHOSPHORBRONZE	MATTE Sn-plated
 广东科斯达电子科技有限公司 GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.				
X.±0.5	X.±5'	USE:	PART NO.:	
.X±0.3	.X±2'	CUSTOMER	L031-1.6-01-T2CB-R	
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰	GCCP-0229	
⊕	UNITS: mm	DR: 吴丹平	SCALE	SHEET
			1 : 1	1 / 1

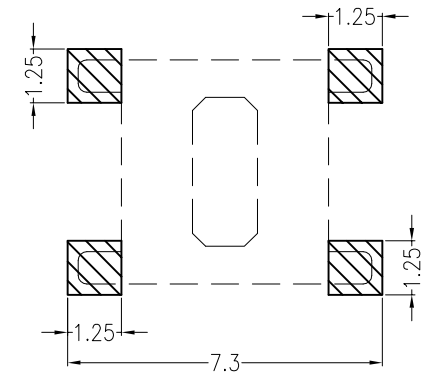
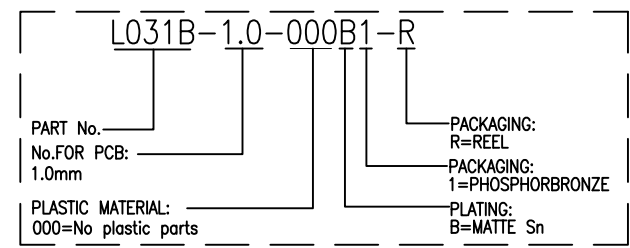
REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	吴丹平	2017.08.12



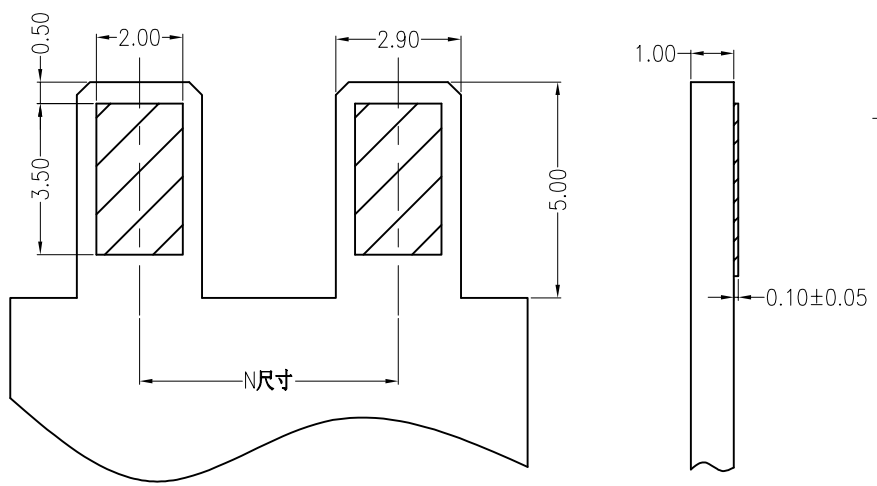
主要技术参数 Main Specifications

板厚 (thickness): 1.0mm
 接触电阻 (Contact resistance): $\leq 20m\Omega$
 额定电压 (Rated voltage): 250 V AC DC
 额定电流 (Rated current): 1.0A AC DC
 温度范围 (Temperature Range): $-45^{\circ}C \sim +125^{\circ}C$

ORDER INFORMATION:



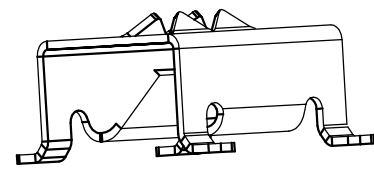
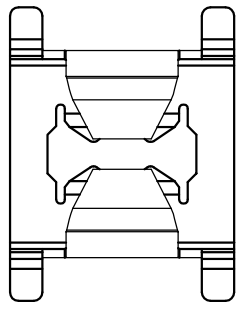
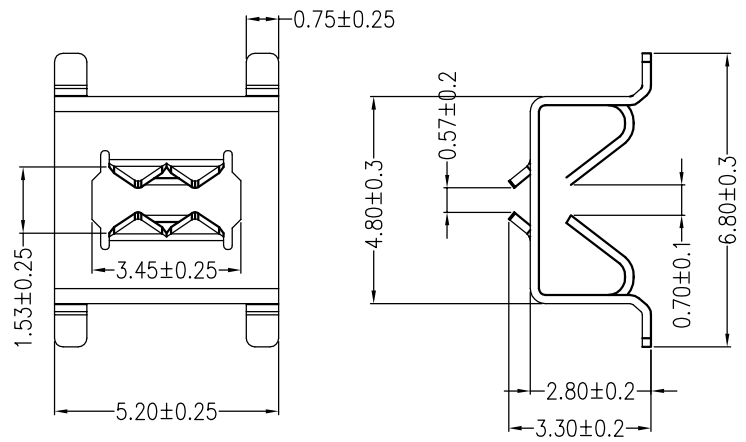
Board Layout



Mating PCB detail

C				
B				
A	CONTACT	1 PCS	PHOSPHORBRONZE	MATTE Sn-plated
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
广东科斯达电子科技有限公司 GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.		TITLE: -- --		
X.±0.5	X.±5'	USE:	PART NO.:	
.X±0.3	.X±2'	CUSTOMER	L031B-1.0-000B1-R	
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰	GCCP-1022	
⊕	UNITS: mm	DR: 吴丹平	SCALE	SHEET
			1 : 1	1 / 1

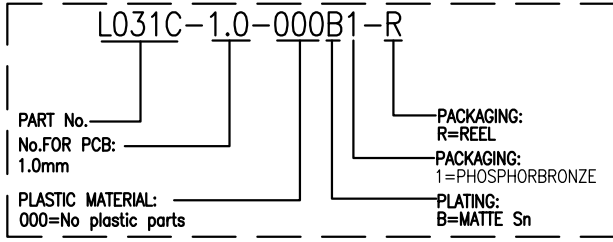
REV	ECN No.	DESCRIPTION	DESIGN	DATE
AO		Release	曾令青	2018.08.24



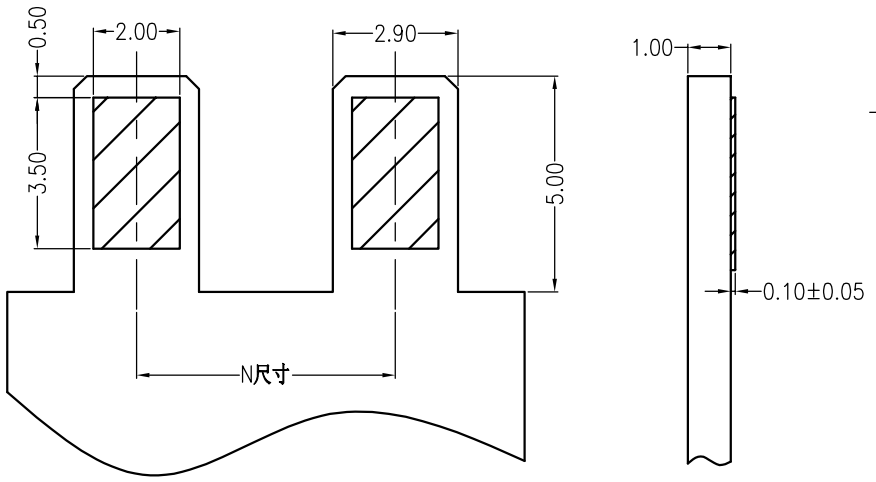
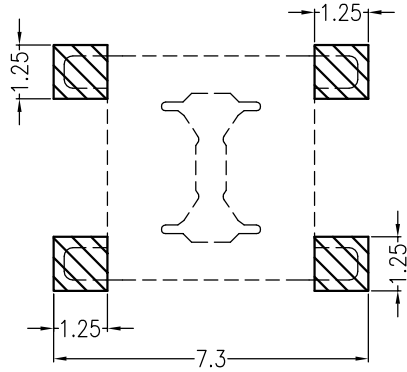
主要技术参数 Main Specifications

板厚 (thickness): 1.0mm
 接触电阻 (Contact resistance): $\leq 20m\Omega$
 额定电压 (Rated voltage): 250 V AC DC
 额定电流 (Rated current): 1.0A AC DC
 温度范围 (Temperature Range): $-45^{\circ}C \sim +125^{\circ}C$

ORDER INFORMATION:



Board Layout



Mating PCB detail

C				
B				
A	CONTACT	1 PCS	PHOSPHORBRONZE	MATTE Sn-plated
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
广东科斯达电子科技有限公司 GUANG DONG KE SI DA ELECTRONIC TECHNOLOGY CO., LTD.		TITLE: -		
X.±0.5	X.±5'	USE: CUSTOMER	PART NO.: L031C-1.0-000B1-R	
.X±0.3	.X±2'	APPD: 邵敬和	DWG NO.: GCCP-1226	
.XX±0.25	.XX±1'	CHKD: 田峰		
--	--	DR: 曾令青	SCALE: 1:1	SHEET: 1/1
⊕	☐	UNITS: mm		